



B8

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Tee O. Chong et al.

Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED  
METHODS

Docket No.: 884.419US1

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Examiner: John Vigushin

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Group Art Unit: 2827

Commissioner for Patents

Attn: MAIL STOP ISSUE FEE

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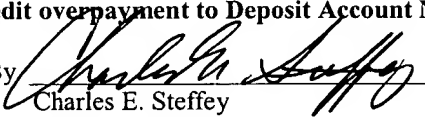
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